



Features:

- Isolated mounting base 3000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- AC/DC Motor drives
- Various rectifiers
- DC supply for PWM inverter

V_{RSM}	V_{RRM}	Type & Outline
900V	800V	MDx200-08-216F3
1100V	1000V	MDx200-10-216F3
1300V	1200V	MDx200-12-216F3
1500V	1400V	MDx200-14-216F3
1700V	1600V	MDx200-16-216F3
1900V	1800V	MDx200-18-216F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	$T_j(^{\circ}C)$	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_c=100^{\circ}C$	150			200	A
$I_{F(RMS)}$	RMS forward current		150			314	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			12	mA
I_{FSM}	Surge forward current	10ms half sine wave	150			7.5	KA
I^2t	I^2T for fusing coordination	$V_R=0.6V_{RRM}$				281	A^2s*10^3
V_{FO}	Threshold voltage		150			0.75	V
r_F	Forward slop resistance					0.88	mΩ
V_{FM}	Peak forward voltage	$I_{FM}=600A$	25			1.38	V
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180° sine' Single side cooled per chip				0.210	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180° sine' Single side cooled per chip				0.08	$^{\circ}C/W$
V_{iso}	Isolation voltage	50Hz, R.M.S, t=1min, $I_{iso}:1mA(max)$		3000			V
F_m	Terminal connection torque(M6)				6.0		N·m
	Mounting torque(M6)				6.0		N·m
T_{stg}	Stored temperature			-40		125	$^{\circ}C$
W_t	Weight				285		g
Outline	216F3						

Peak forward Voltage Vs. Peak forward Current

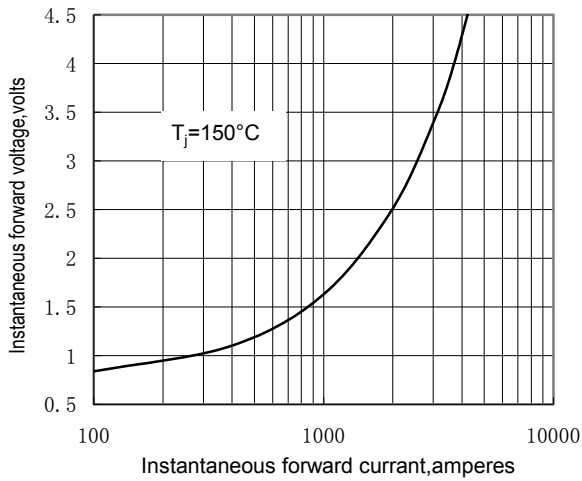


Fig.1

Max. junction To case Thermal Impedance Vs. Time

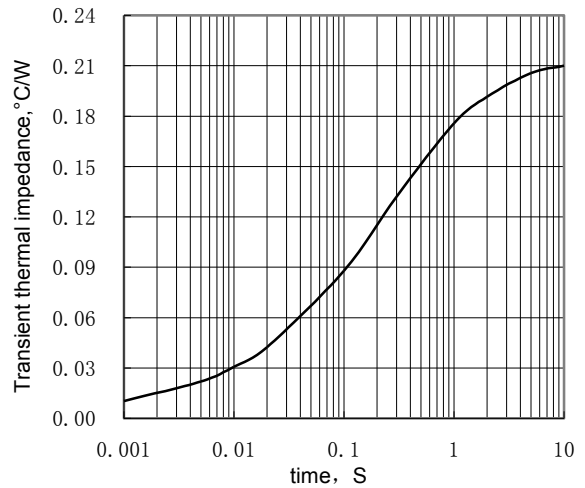


Fig.2

Max. Power Dissipation Vs. Mean forward Current

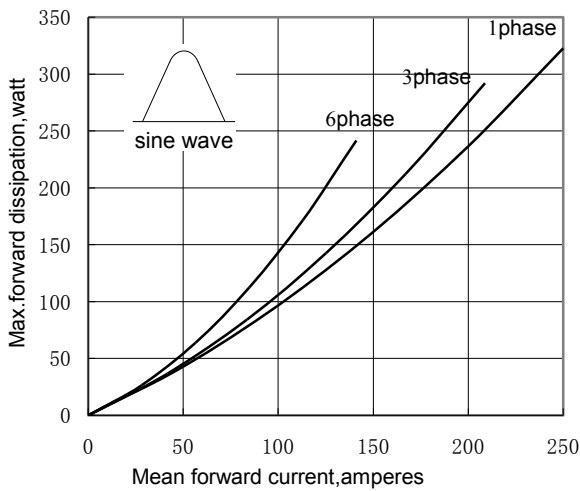


Fig.3

Max. case Temperature Vs. Mean forward Current

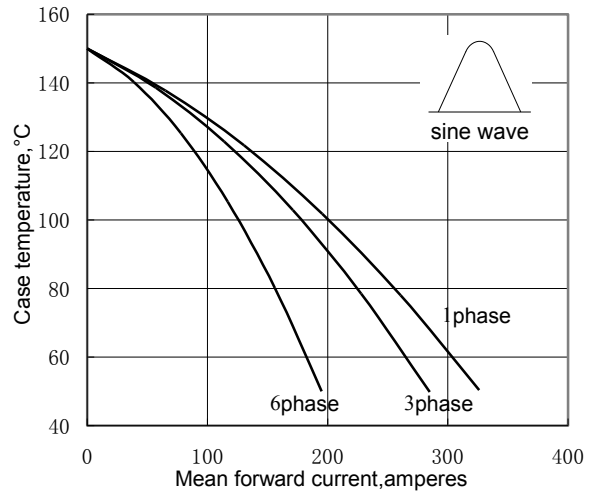


Fig.4

Max. Power Dissipation Vs. Mean forward Current

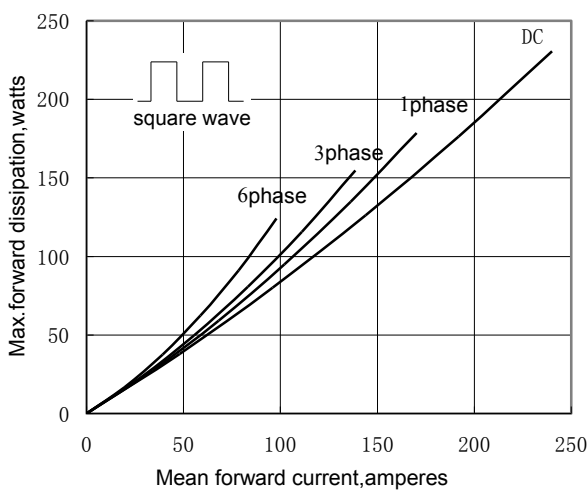


Fig.5

Max. case Temperature Vs. Mean forward Current

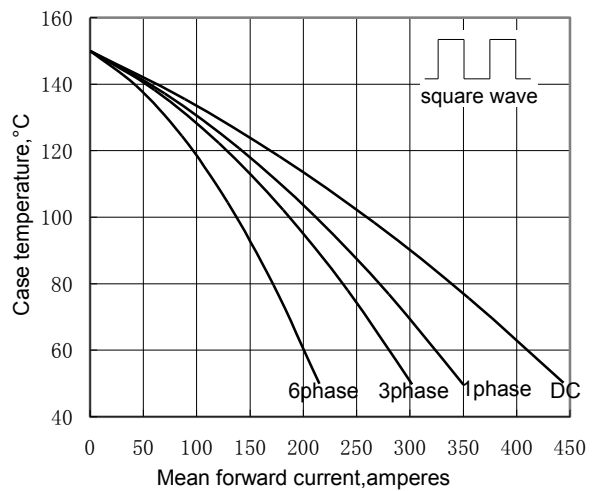


Fig.6

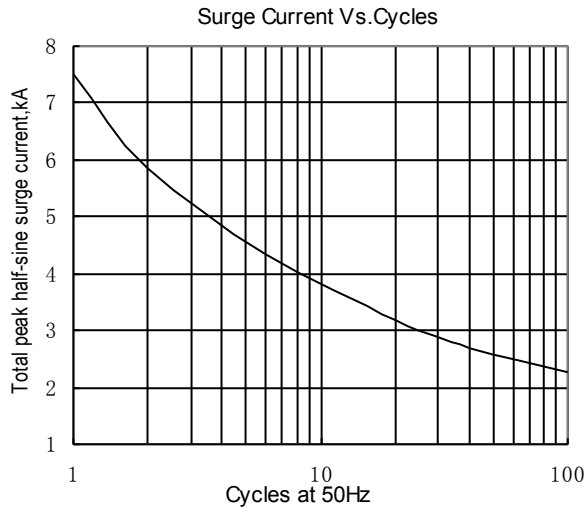


Fig.7

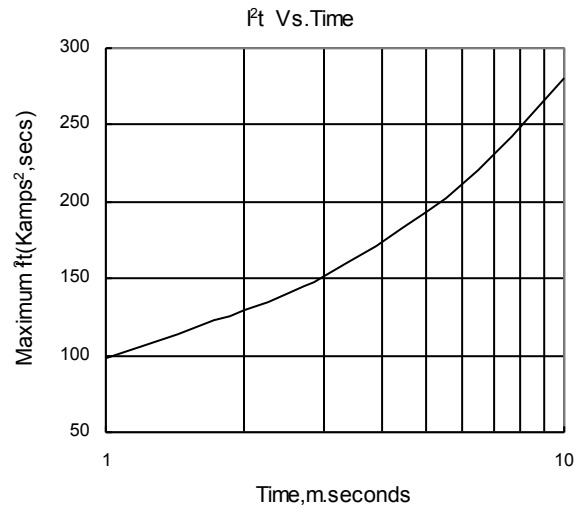
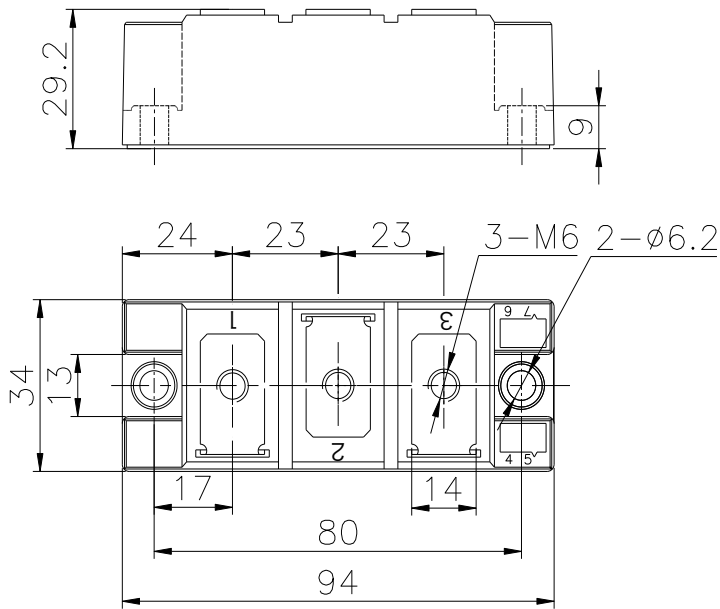


Fig.8

Outline:



216F3

